10061913-103TLF - PCI Express : Surface Mount Card Edge Connector, 164 Positions

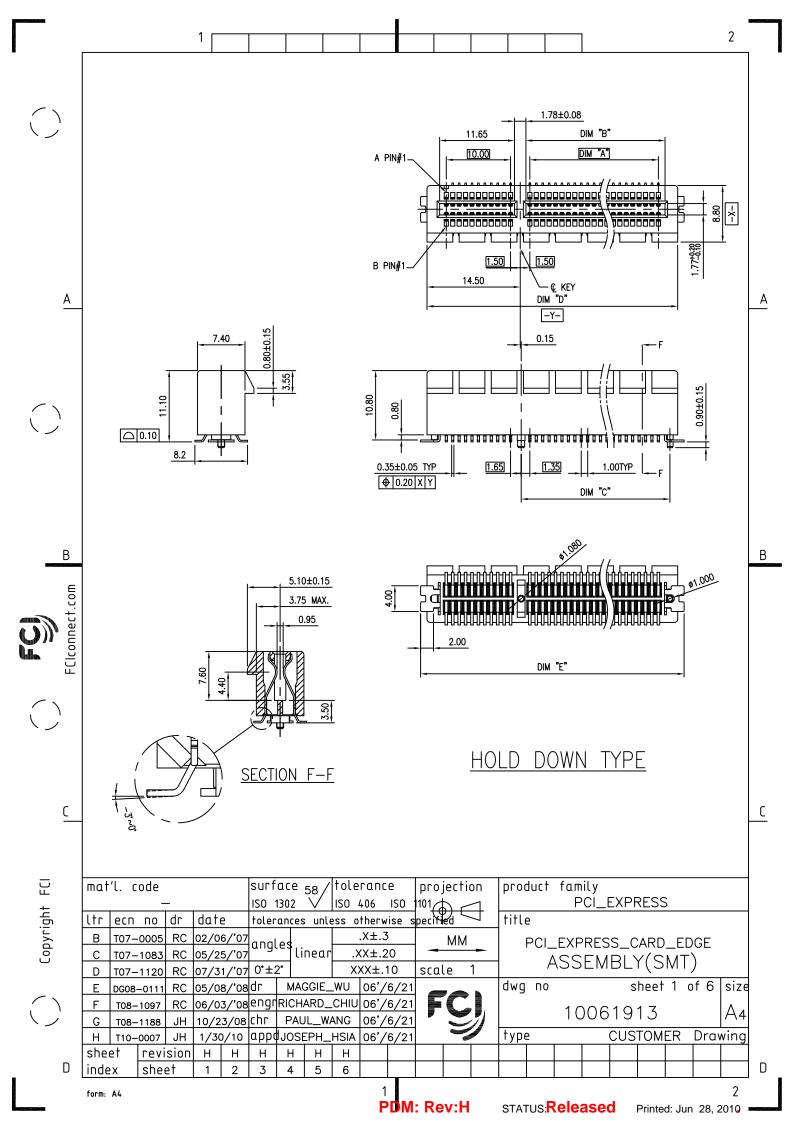


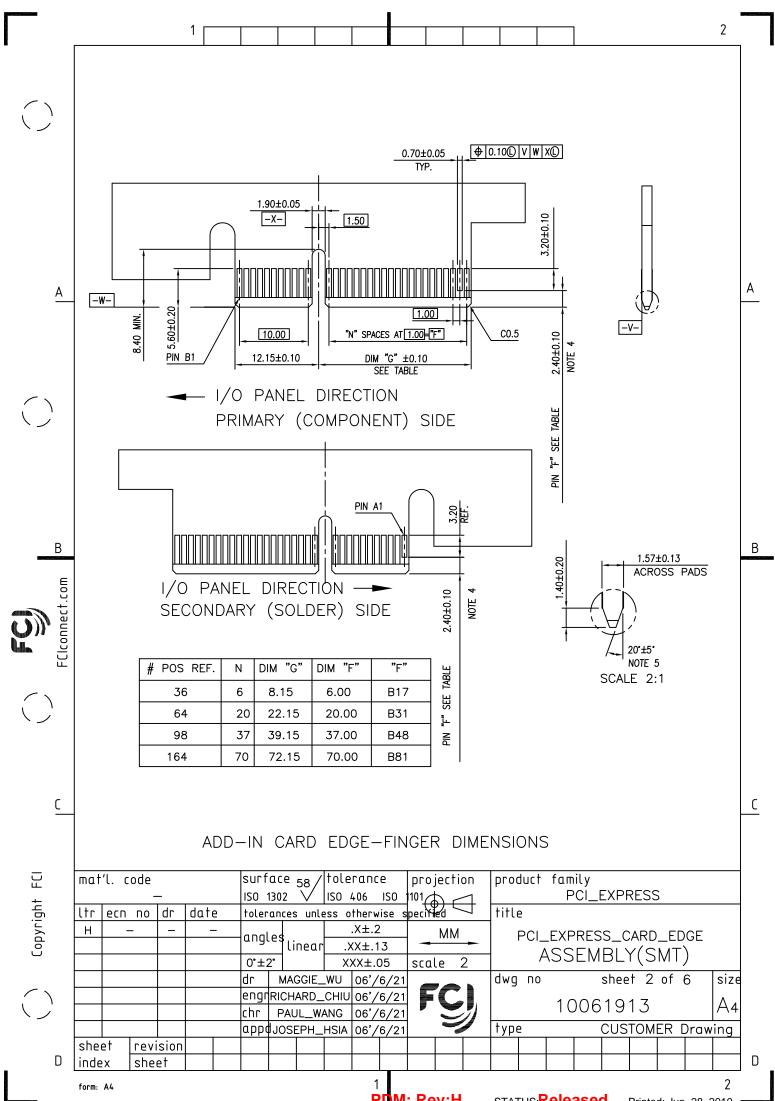




Specifications

General						
Component Type	Surface Mount Connector					
Number of contacts (Total)	164 (x16)					
Orientation (Features)	Plastic Post					
Dimensional						
Thickness (Board)	1.56 mm (0.062 in.)					
PCB Thickness (Add-In)	1.57 mm (0.062 in.)					
Electrical						
Current rating	1.1 amps per contact					
Resistance (Contact)	30 milli ohms max. (Initial) with 10 milli ohms max. change after Exposure Testing					
Resistance (Insulation)	1000 M-ohms					
Voltage rating	300V AC					
Mechanical						
Durability (Mating cycles)	50					
Withdrawal Force	0.15N minmum per Contact pair					
Mating force	1.15N maximum per Contact pair					
Mounting						
Solder process	Reflow Solder					
Physical						
Color (Housing)	Black					
Material (Contact)	Copper Alloy					
Material (Housing)	High - Temperature Nylon, Glass - Filled, UL94V-0					
Plating (Contact area)	0.76 μm (30 μin.) Gold over 1.27 μm (50 μin.) Nickel					
Plating (Solder area)	2.54 μm (100 μin.) Tin over 1.27 μm (50 μin.) Nickel					
Temperature (Range)	-55°C to +85°C					
Approvals / Certifications						
Approvals / Certifications	UL Approved					
Other Features						
Packaging (Type)	Tray without Cap					

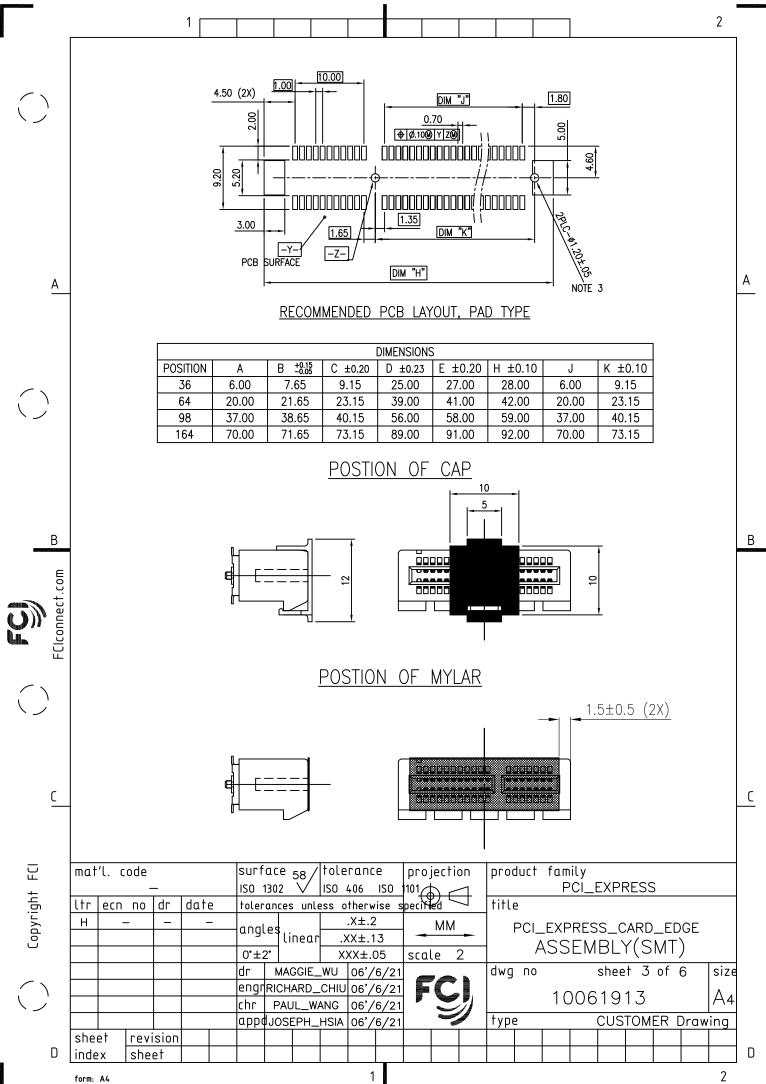




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NOTES:

1.MATERIAL:

HOUSING: NYLON, GLASS FILLED UL94V-0 RATE, SUITABLE FOR I.R SOLDERING.

TERMINAL: COPPER ALLOY

PLATING: 50u" NICKEL UNDERPLATE ALL OVER
CONTACT AREA PLATING — SEE PRODUCT NUMBER CODE

SOLDER TAIL: TIN 100u" OVER 50u" NICKEL

METAL PADS: COPPER ALLOY FINISH: 100u" TIN OVER 50u" NICKEL 2.PRODUCT SPECIFICATION: GS-12-390

3THE HORIZONTAL AXIS FOR THE PAD PATTERN IS ESTABLISHED BY

A LINE THROUGH THE CENTER OF THE TWO Ø1.0 HOLES.

THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER

OF DATUM -Z-

(4)NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1.

SCHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

7.RoHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

"LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C PEAK TEMPERATURE FOR 5 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.

PRODUCT NUMBER CODE

10061913-<u>x x x x x L f</u>

HOUSING COLOR OPTIONS

0-WHITE 1-BLACK

LEAD FREE

PACKAGING OPTIONS

T-TRAY PACKAGING WITHOUT CAP
R-TAPE & REEL PACKING WITHOUT CAP OR MYLAR (FOR
36P & 64P OPTION ONLY)
P-TAPE & REEL PACKING WITH CAP (FOR 36P & 64P OPTION ONLY)

C-TRAY PACKAGING WITH CAP

M-TAPE & REEL PACKING WITH MYLAR (FOR 36P & 64P OPTION ONLY)

N-TRAY PACKAGING WITH MAYLAR

Y-HARD TRAY (FOR 164P ONLY)

Z-HARD TRAY PACKAGING WITH MAYLAR (FOR 164P ONLY)

TERMINAL PLATING OPTIONS

0-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA -1-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA --

TIN TAIL AREA ---- COMPATIBLE RoHS

2 - 98---- COMPATIBLE RoHS

2-50u" Ni UNDERPLATE GOLD FLASH CONTACT AREA

100u" TIN TAIL AREA ---- COMPATIBLE RoHS

POS OPTIONS 0 - 36

1-64

3 - 164

mat'l. code			surface ₅₈ / tolerance			rance	projection	product family				
			ISO 1302 V ISO 406 ISO tolerances unless otherwise s			406 ISO	101	PCI_EXPRESS				
ltr	ecn no	d٢	date	tolero	ances unle	ess o	therwise s	pecified	title			
Н	-	_	_	angl			.X±.2	ММ	PCI_EXPRESS_CARD_EDGE			
				ungu	🖺 linear	· .)	XX±.13		ASSEMBLY(SMT)			
				0°±2		X	XX±.05	scale 2				
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				chr								
				appd					type	CUSTOMER Drav	wing	

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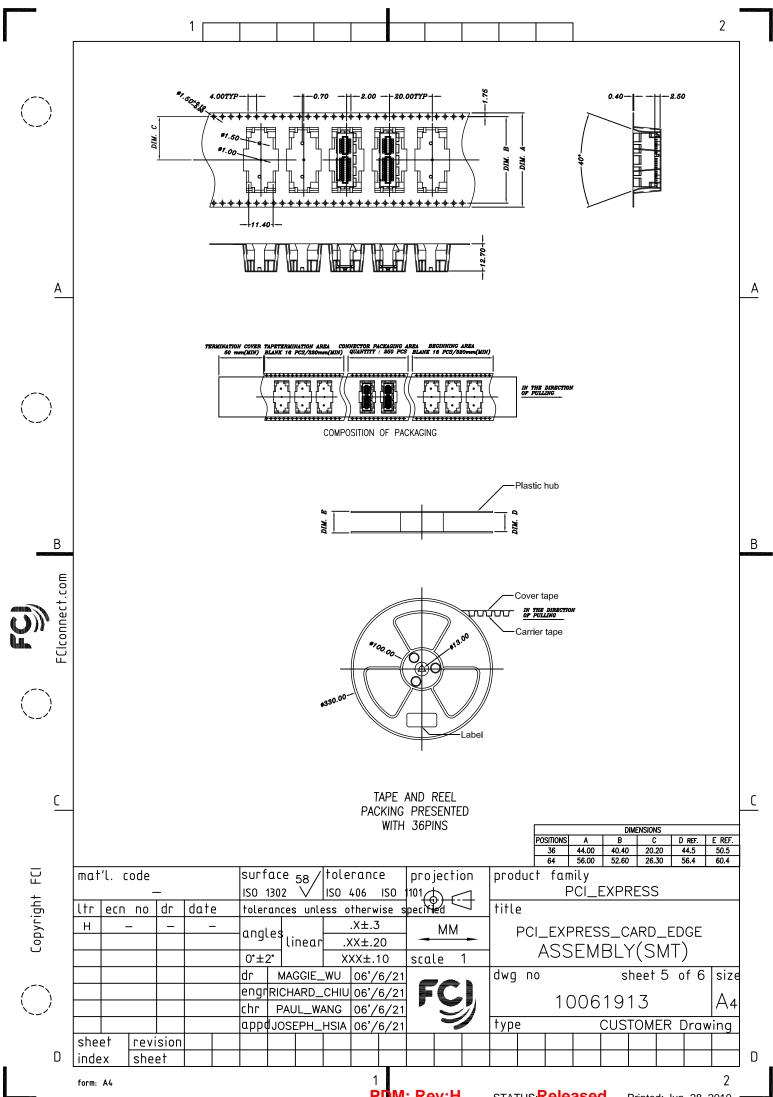
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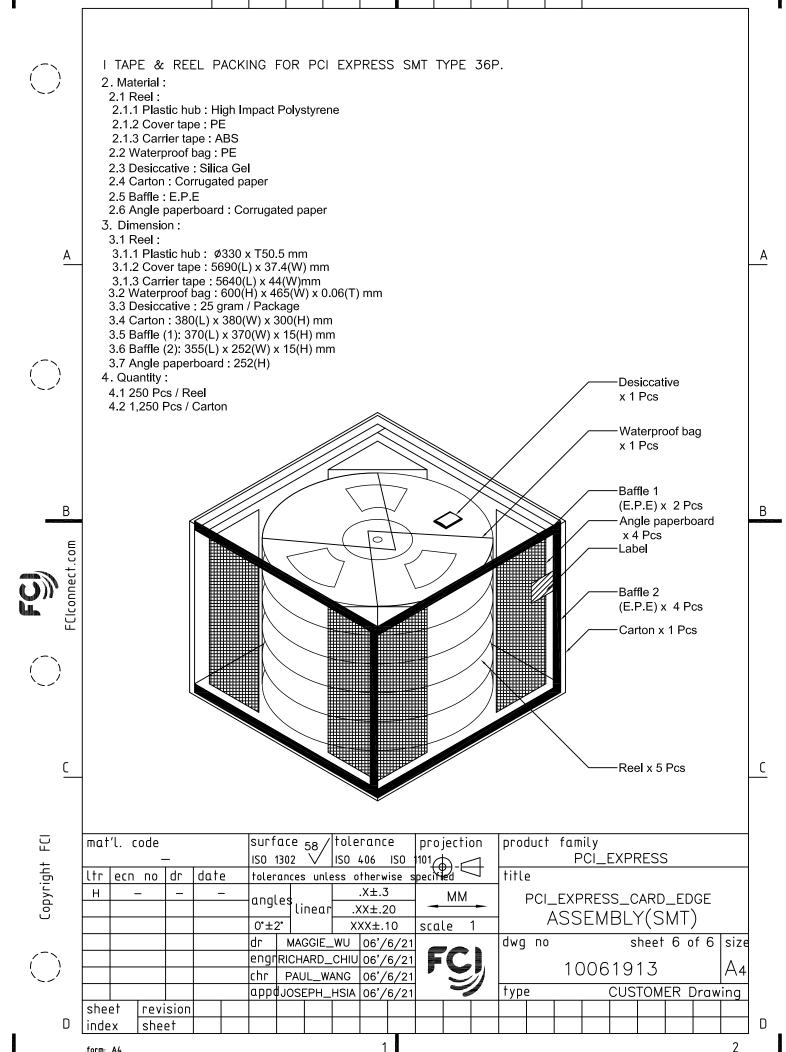
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